

Technical Data

BioSLIP® EA-65

Modified stearic based wax

Product Description:

BioSLIP[®] EA-65 is a bio-based modified stearic based wax. The bio-based component is derived from plant based stearic acid and blended with synthetic wax to provide exceptional abrasion resistance.

Application:

BioSLIP[®] EA-65 has been developed as a performance additive to enhance abrasion resistance, provide uniform gloss reduction and improve block resistance in both inks and coatings. It is ideally suited for paper, wood, plastic and metal coatings. Incorporate with high-speed mixing techniques.

Recommended Level: Inks/Coatings: 1 to 4%

Features and Benefits:

Abrasion/rub/block Resistance
Matting
Rub Resistance
Block Resistance

Typical Properties:

*	Appearance: Specific Gravity:	Off White Powder 0.96
*	Particle Size Mean Value:	5 µm
*	99% of Particle Under:	15 µm
*	NPIRI Grind:	3.5 Max
*	Hegman Grind:	6.5 – 7.0
*	DSC Melting Point:	147°C

Regulatory Status

The components of this product are listed on multiple chemical inventories. For specific information on the applicable chemical inventories, please refer to the product SDS.

Safety, Shipping and Handling

For complete shipping, handling, health and safety information please contact your regional Customer Service Representative. Please contact them at your convenience for instructions and Material Safety Data Sheets, the contact information is located below.

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